

UF28150J



RF Power MOSFET Transistor
150W, 100MHz-500MHz, 28V

M/A-COM Products
Released; RoHS Compliant

Features

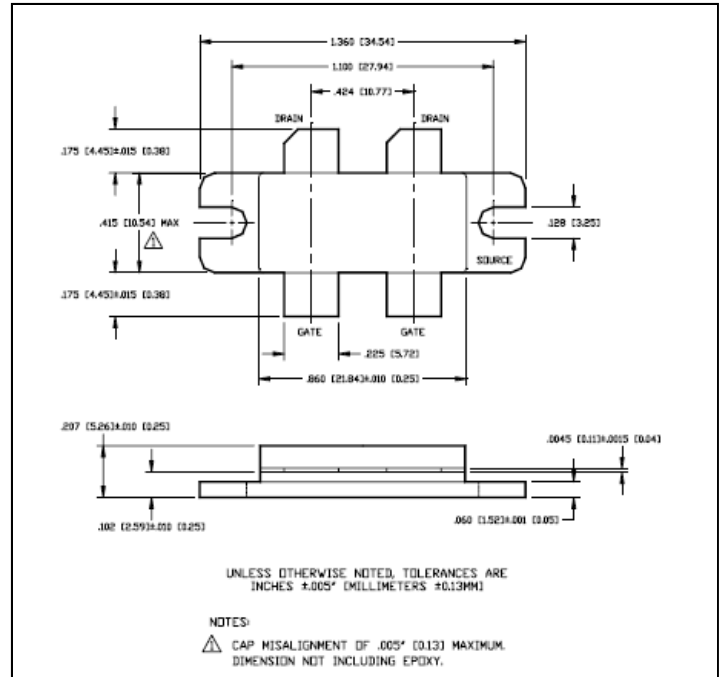
- DMOS structure
- Lower capacitance for broadband operation
- Common source configuration

ABSOLUTE MAXIMUM RATINGS^{1, 2, 3}

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V_{DS}	65	V
Gate-Source Voltage	V_{GS}	20	V
Drain-Source Current	I_{DS}	16*	A
Power Dissipation	P_D	389	W
Junction Temperature	T_J	200	°C
Storage Temperature	T_{STG}	-65 to +150	°C
Thermal Resistance	Θ_{JC}	0.45	°C/W

1. Exceeding any one or combination of these limits may cause permanent damage to this device.
2. M/A-COM does not recommend sustained operation near these maximum limits.
3. At 25°C Tcase, unless noted.

Package Outline



ELECTRICAL SPECIFICATIONS: 25°C

Parameter	Test Conditions	Units	Min.	Max.
Drain-Source Breakdown Voltage	$V_{GS} = 0.0 \text{ V}$, $I_{DS} = 20.0 \text{ mA}^*$	BV_{DSS}	65	—
Drain-Source Leakage Current	$V_{DS} = 28.0 \text{ V}$, $V_{GS} = 0.0 \text{ V}^*$	I_{DSS}	—	4.0
Gate-Source Leakage Current	$V_{GS} = 20 \text{ V}$, $V_{DS} = 0.0 \text{ V}^*$	I_{GSS}	—	4.0
Gate Threshold Voltage	$V_{DS} = 10.0 \text{ V}$, $I_{DS} = 400.0 \text{ mA}^*$	$V_{GS(TH)}$	2.0	6.0
Forward Transconductance	$V_{DS} = 10.0 \text{ V}$, $I_{DS} = 4000.0 \text{ mA}$, $\Delta V_{GS} = 1.0 \text{ V}$, 80µs pulse*	G_M	2.0	—
Input Capacitance	$V_{DS} = 28.0 \text{ V}$, $F = 1.0 \text{ MHz}^*$	C_{ISS}	—	180
Output Capacitance	$V_{DS} = 28.0 \text{ V}$, $F = 1.0 \text{ MHz}^*$	C_{OSS}	—	120
Reverse Capacitance	$V_{DS} = 28.0 \text{ V}$, $F = 1.0 \text{ MHz}^*$	C_{RSS}	—	32
Power Gain	$V_{DD} = 28.0 \text{ V}$, $I_{DQ} = 400.0 \text{ mA}$, $P_{OUT} = 150.0 \text{ W}$, $F = 500 \text{ MHz}$	G_P	8	—
Drain Efficiency	$V_{DD} = 28.0 \text{ V}$, $I_{DQ} = 400.0 \text{ mA}$, $P_{OUT} = 150.0 \text{ W}$, $F = 500 \text{ MHz}$	η_D	55	—
Load Mismatch Tolerance	$V_{DD} = 28.0 \text{ V}$, $I_{DQ} = 400.0 \text{ mA}$, $P_{OUT} = 150.0 \text{ W}$, $F = 500 \text{ MHz}$	VSWR-T	—	10:1**

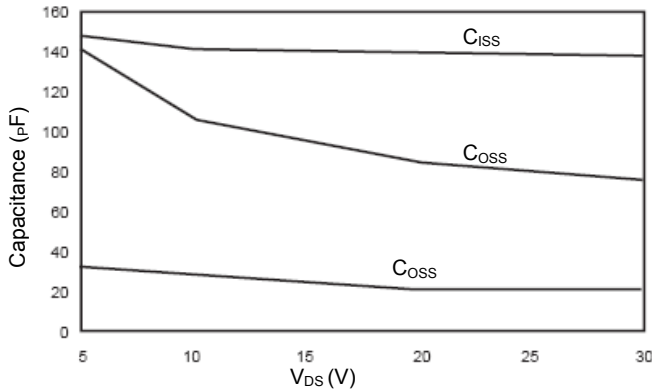
Notes:

* Per side

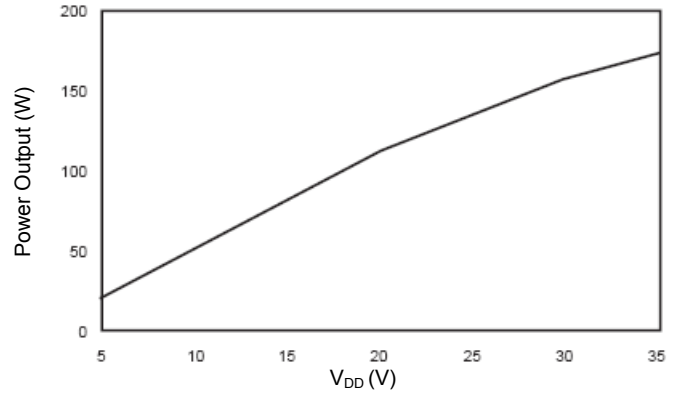
** At all phase angles

Typical Broadband Performance Curves

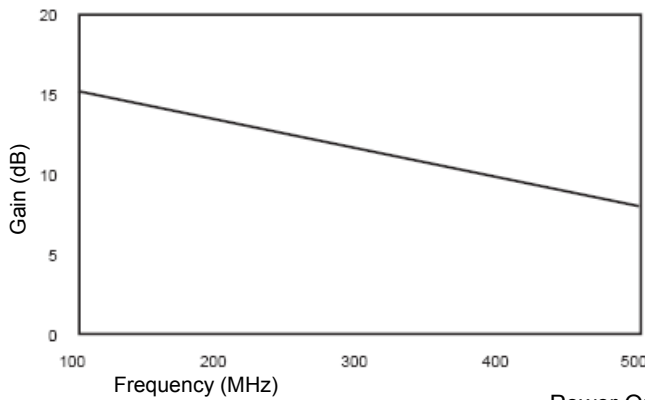
Capacitance vs Voltage
 $F=1.0\text{ MHz}$



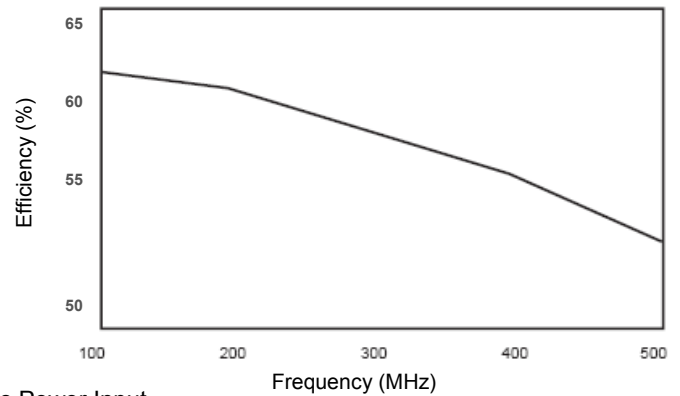
Power Output vs Voltage
 $P_{IN}=24\text{ W } I_{DQ}=400\text{ mA } F=500\text{ MHz}$



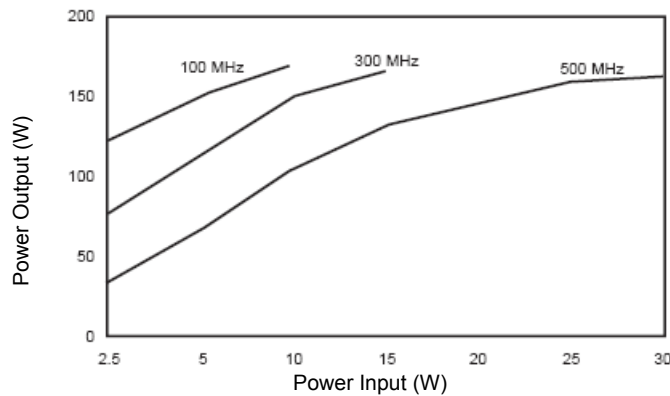
Gain vs Frequency
 $V_{DD}=28\text{ V } P_{OUT}=100\text{ W } I_{DQ}=400\text{ mA}$



Efficiency vs Frequency
 $V_{DD}=28\text{ V } I_{DQ}=400\text{ mA } P_{OUT}=150\text{ W}$



Power Output vs Power Input
 $V_{DD}=28\text{ V } I_{DQ}=400\text{ mA}$



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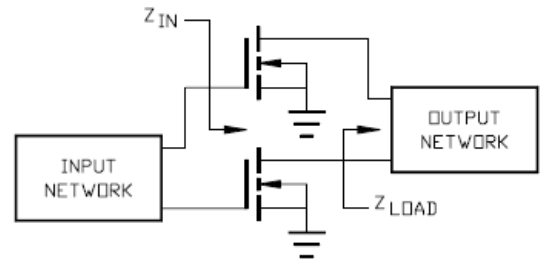
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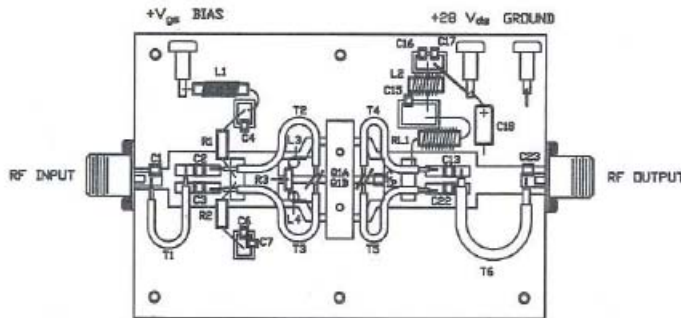
TYPICAL OPTIMUM DEVICE IMPEDANCES

F (MHz)	Z _{IN} (Ω)	Z _{LOAD} (Ω)
100	3.7 - j5.9	3.0 - j0.7
300	2.7 - j5.9	2.6 - j0.55
500	2.5 - j2.9	2.5 - j0.5

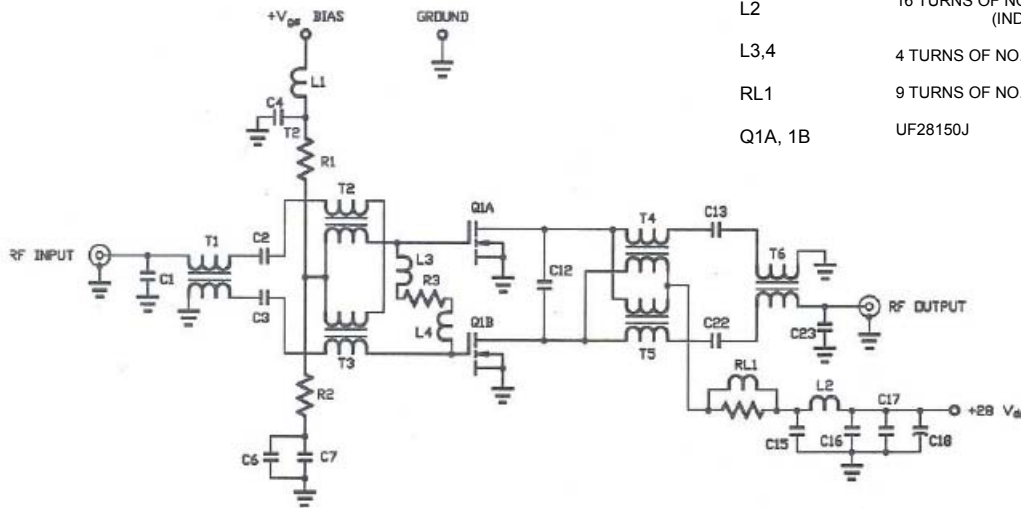
V_{DD} = 28V, I_{DQ} = 400mA, P_{OUT} = 150W



PARTS LIST



- | | |
|---------------|--|
| C23 | 1.0pF |
| C1 | 9.1pF |
| C12 | 11pF |
| C2, 3, 13, 22 | 270pF |
| C7, 16 | 680pF |
| C4, 6, 15, 17 | .015uF |
| C18 | 50uF 50V |
| R1 | 11K OHM .25 W. 10% |
| R2 | 47 OHM .05 W. 10% |
| R3 | 12 OHM .25 W. 10% |
| T1 | 2.50' OF 50 OHM (.85' OD) SEMI-RIGID CABLE |
| T2,3,4,5 | 2.50' OF 10 OHM (.70' OD) SEMI-RIGID CABLE |
| T6 | 2.50' OF 50 OHM (.141' OD) SEMI-RIGID CABLE |
| L1 | 5uH |
| L2 | 16 TURNS OF NO. 18 AWG ON TORID CORE
(INDIANA GENERAL F6278-Q1) |
| L3,4 | 4 TURNS OF NO. 18 AWG ON .125 DIAMETER |
| RL1 | 9 TURNS OF NO. 18 AWG ON 15 OHM 2 W. 10% RESISTOR |
| Q1A, 1B | UF28150J |



HANDLING PROCEDURES: STATIC SENSITIVITY

Please observe the following precautions to avoid damage:

DMOS devices are sensitive to electrostatic discharge (ESD) and can be damaged by static electricity. Proper ESD control techniques should be used when handling these devices.